

# 1.8V PHASE LOCKED LOOP DIFFERENTIAL 1:10 SDRAM CLOCK DRIVER

### IDTCSPU877D

### **FFATURFS**:

- · 1 to 10 differential clock distribution
- Optimized for clock distribution in DDR2 (Double Data Rate) SDRAM applications
- · Operating frequency: 125MHz to 340MHz
- Very low skew: ≤40ps
- Very low jitter: ≤40ps
- 1.8V AVDD and 1.8V VDDQ
- · CMOS control signal input
- · Test mode enables buffers while disabling PLL
- · Low current power-down mode
- Tolerant of Spread Spectrum input clock
- · Available in 52-Ball VFBGA and 40-pin MLF packages

### APPLICATIONS:

- Meets or exceeds JEDEC standard 82.8 for registered DDR2 clock driver
- Along with SSTU32864/65/66, DDR2 register, provides complete solution for DDR2 DIMMs

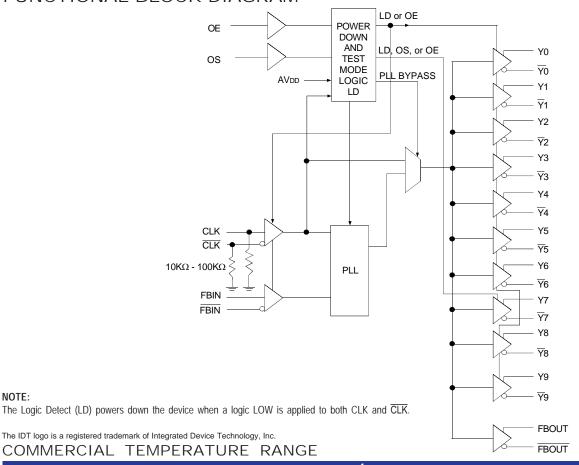
### **DESCRIPTION:**

The CSPU877D is a PLL based clock driver that acts as a zero delay buffer to distribute one differential clock input pair(CLK,  $\overline{\text{CLK}}$ ) to 10 differential output pairs  $(\overline{\text{Y}[0:9]}, \text{Y}[0:9])$  and one differential pair of feedback clock output (FBOUT,  $\overline{\text{FBOUT}}$ ). External feedback pins (FBIN,  $\overline{\text{FBIN}}$ ) for synchronization of the outputs to the input reference is provided. OE, OS, and AVDD control the power-down and test mode logic. When AVDD is grounded, the PLL is turned off and bypassed for test mode purposes. When the differential clock inputs (CLK,  $\overline{\text{CLK}}$ ) are both at logic low, this device will enter a low power-down mode. In this mode, the receivers are disabled, the PLL is turned off, and the output clock drivers are disabled, resulting in a current consumption device of less than 500µA.

The CSPU877D requires no external components and has been optimised for very low phase error, skew, and jitter, while maintaining frequency and duty cycle over the operating voltage and temperature range. The CSPU877D, designed for use in both module assemblies and system motherboard based solutions, provides an optimum high-performance clock source.

The CSPU877D is available in Commercial Temperature Range (0°C to +70°C). See Ordering Information for details.

## FUNCTIONAL BLOCK DIAGRAM



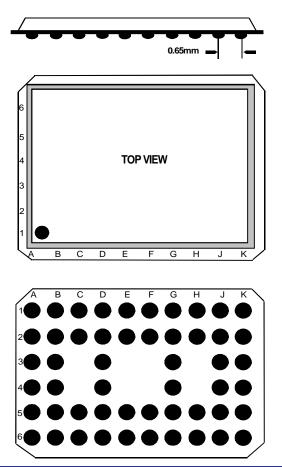
AUGUST 2004

## PIN CONFIGURATION

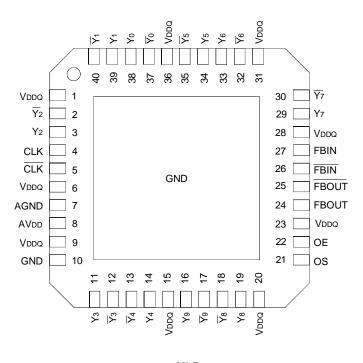
		I	I				ı			
6	Y6	<u>Y6</u>	<del>Y</del> 7	<b>Y</b> 7	FBIN	FBIN	FBOUT	FBOUT	Y8	<u>Y8</u>
5	<b>Y</b> 5	GND	GND	os	VDDQ	OE	VDDQ	GND	GND	<del>Y</del> 9
4	<u>Y</u> 5	GND	NB	VDDQ	NB	NB	VDDQ	NB	GND	<b>Y</b> 9
3	<u>Y</u> 0	GND	NB	VDDQ	NB	NB	VDDQ	NB	GND	Y4
2	Y0	GND	GND	VDDQ	VDDQ	VDDQ	VDDQ	GND	GND	<u>Y4</u>
1	Y1	<u>Y1</u>	Y2	Y2	CLK	CLK	AGND	AVDD	<b>Y</b> 3	<u>Y3</u>
	Α	В	С	D	Е	F	G	Н	J	K

VFBGA TOP VIEW

# 52 BALL VFBGA PACKAGE LAYOUT



## **PIN CONFIGURATION**



### MLF TOP VIEW

## ABSOLUTE MAXIMUM RATINGS(1,2)

Symbol	Rating	Max	Unit
Vddq, AVdd	Supply Voltage Range	-0.5 to +2.5	V
VI <sup>(3)</sup>	Input Voltage Range	-0.5 to VDDQ + 0.5	V
Vo <sup>(3)</sup>	Voltage range applied to any	-0.5 to VDDQ + 0.5	V
	output in the high or low state		
lık	Input clamp current	±50	mA
(VI <0)			
Іок	Output Clamp Current	±50	mA
(Vo <0 or			
Vo > Vddq)			
lo	Continuous Output Current	±50	mA
(Vo =0 to VDDQ)			
VDDQ or GND	Continuous Current	±100	mA
TSTG	Storage Temperature Range	- 65 to +150	°C

### NOTES:

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause
  permanent damage to the device. This is a stress rating only and functional operation of
  the device at these or any other conditions above those indicated in the operational
  sections of this specification is not implied. Exposure to absolute maximum rating
  conditions for extended periods may affect reliability.
- The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.
- The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed. This value is limited to 2.5V max.

### CAPACITANCE<sup>(1)</sup>

Parameter	Description	Min.	Тур.	Max.	Unit
CIN	Input Capacitance	2	_	3	pF
	VI = VDDQ or GND				
CιΔ	Delta Input Capacitance			0.25	pF
	CLK, CLK, FBIN, FBIN				
CL	Load Capacitance	_	10	_	pF

### NOTE

1. Unused inputs must be held high or low to prevent them from floating.

## RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min.	Тур.	Max.	Unit
AV <sub>DD</sub> <sup>(1)</sup>	Supply Voltage		VDDQ		V
VDDQ	I/O Supply Voltage	1.7	1.8	1.9	V
TA	Operating Free-Air Temperature	0	_	+70	°C

### NOTE:

1. The PLL is turned off and bypassed for test purposes when AVpp is grounded. During this test mode, Vppp remains within the recommended operating conditions and no timing parameters are guaranteed.

# PIN DESCRIPTION (VFBGA)

Pin Name	Pin Number	Description
AGND	G1	Ground for 1.8V analog supply
AVdd	H1	1.8V analog supply
CLK, CLK	E1, F1	Differential clock input with a $10 K\Omega$ to $100 K\Omega$ pulldown resistor
FBIN, FBIN	E6, F6	Feedbackdifferentialclockinput
FBOUT, FBOUT	G6, H6	Feedbackdifferential clock output
GND	B2 - B5, C2, C5, H2, H5, J2 - J5	Ground
VDDQ	D2 - D4, E2, E5, F2, G2 - G5	1.8V supply
OE	F5	Output Enable
OS	D5	Output Select (tied to GND or VDDQ)
<u>Y[0:9]</u>	A3, A4, B1, B6, C1, C6, K1, K2, K5, K6	Buffered output of input clock, CLK
Y[0:9]	A1, A2, A5, A6, D1, D6, J1, J6, K3, K4	Buffered output of input clock, CLK
NB		No Ball

# PIN DESCRIPTION (MLF)

Pin Name	Pin Number	Description
AGND	7	Ground for 1.8V analog supply
AVdd	8	1.8V analog supply
CLK, CLK	4, 5	Differential clock input with a $10 K\Omega$ to $100 K\Omega$ pulldown resistor
FBIN, FBIN	26, 27	Feedback differential clock input
FBOUT, FBOUT	24,25	Feedback differential clock output
GND	10	Ground
VDDQ	1, 6, 9, 15, 20, 23, 28, 31, 36	1.8V supply
OE	22	Output Enable
OS	21	Output Select (tied to GND or VDDQ)
Y[0:9]	3, 11, 14, 16, 19, 29, 33, 34, 38, 39	Buffered output of input clock, CLK
<u>Y[0:9]</u>	2, 12, 13, 17, 18, 30, 32, 35, 37, 40	Buffered output of input clock, CLK
NB		No Ball

### FUNCTION TABLE(1,2)

		INPUT	S		OUTPUTS				
AVDD	OE	os	CLK	CLK	Υ	Y	FBOUT	FBOUT	PLL
GND	Н	Х	L	Н	L	Н	L	Н	OFF
GND	Н	Х	Н	L	Н	L	Н	L	OFF
GND	L	Н	L	Н	L(z)	L(z)	L	Н	OFF
					L(z)	L(z)			
GND	L	L	Н	L	<b>Y</b> 7	<del>Y</del> 7	Н	L	OFF
					Active	Active			
1.8V (nom)	L	Н	L	Н	L(z)	L(z)	L	Н	ON
					L(z)	L(z)			
1.8V (nom)	L	L	Н	L	<b>Y</b> 7	<del>Y</del> 7	Н	L	ON
					Active	Active			
1.8V (nom)	Н	Х	L	Н	L	Н	L	Н	ON
1.8V (nom)	Н	Х	Н	L	Н	L	Н	L	ON
1.8V (nom)	Х	Х	L <sup>(3)</sup>	L <sup>(3)</sup>	L(z)	L(z)	L(z)	L(z)	OFF
Х	Х	Х	Н	Н	Reserved				

#### NOTES:

- 1. H = HIGH Voltage Level
  - L = LOW Voltage Level
  - X = Don't Care
- 2. L(z) means the outputs are disabled to a LOW state, meeting the looL limit in DC Electrical Characteristics table.
- 3. The device will enter a low power-down mode when CLK and  $\overline{\text{CLK}}$  are both at logic LOW.

# DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:

Commercial:  $TA = 0^{\circ}C$  to  $+70^{\circ}C$ 

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Vik	Input Clamp Voltage (All Inputs)	VDDQ = 1.7V, II = -18mA	_	_	-1.2	V
VIL <sup>(2)</sup>	Input LOW Voltage (OE, OS, CLK, CLK)		_	_	0.35VDDQ	V
VIH <sup>(2)</sup>	Input HIGH Voltage (OE, OS, CLK, CLK)		0.65VDDQ	_	_	
VIN <sup>(1)</sup>	Input Signal Voltage		-0.3	_	VDDQ + 0.3	V
VID(DC) <sup>(2)</sup>	DC Input Differential Voltage		0.3		VDDQ + 0.4	V
Vod <sup>(3)</sup>	Output Differential Voltage	AVDD/VDDQ = 1.7V	0.5	_	_	V
Voн	Output HIGH Voltage	IOH = -100μA, VDDQ = 1.7V to 1.9V	VDDQ - 0.2		_	V
		IOH = -9mA, VDDQ = 1.7V	1.1		_	
Vol	Output LOW Voltage	IOL = 100μA, VDDQ = 1.7V to 1.9V			0.1	V
		IOL = 9mA, VDDQ = 1.7V			0.6	
IODL	Output Disabled LOW Current	OE = L, VODL = 100mV, AVDD/VDDQ = 1.7V	100	_	_	μΑ
lin	Input Current CLK, CLK	AVDD/VDDQ = Max., VI = 0V to VDDQ			±250	μА
	OE, OS, FBIN, FBIN				±10	
Iddld	Static Supply Current (IDDQ and IADD)	AVDD/VDDQ = Max., CLK and $\overline{\text{CLK}}$ = GND			500	μΑ
IDD	Dynamic Power Supply Current	AVDD/VDDQ = Max., CLK = 270MHz			300	mA
	(IDDQ and IADD) <sup>(4,5)</sup>					

### NOTES:

- 1. Vin specifies the allowable DC excursion of each different output.
- 2. VID is the magnitude of the difference between the input level on CLK and the input level on CLK and TCLK VIH and VIL limits are used to define the DC LOW and HIGH levels for the power down mode.
- 3. Vop is the magnitude of the difference between the true output level and the complementary level.
- 4. All Outputs are left open (unconnected to PCB).
- 5. Total IDD = IDDD + IADD = FCK \* CPD \* VDDD, for CPd = (IDDD + IADD) / (FCK \* VDDD) where FCK is the input frequency, VDDD is the Power Dissipation Capacitance.

### TIMING REQUIREMENTS

Symbol	Parameter	Min.	Max.	Unit
fclk	Operating Clock Frequency <sup>(1,2,3)</sup>		340	MHz
	Application Clock Frequency <sup>(1,3,4)</sup>	160	340	MHz
toc	Input Clock Duty Cycle	40	60	%
t_	Stabilization Time <sup>(5)</sup>	_	15	μS

### NOTES:

- 1. The PLL will track a spread spectrum clock input.
- 2. Operating clock frequency is the range over which the PLL will lock, but may not meet all timing specifications. To be used only for low speed system debug.
- 3. Will lock to input frequency as low as 30MHz at room temperature and nominal or higher supply voltage (1.8V 1.9V).
- 4. Application clock frequency is the range over which timing specifications apply.
- 5. Stabilization time is the time required for the integrated PLL circuit to obtain phase lock of its feedback signal to its reference signal after power up. During normal operation, the stabilization time is also the time required for the PLL circuit to obtain phase lock of its feedback signal to its reference signal when CLK and CLK go to a logic LOW state, enters the power-down mode, and later return to active operation. CLK and CLK may be left floating after they have been driven LOW for one complete clock cycle.

# AC ELECTRICAL CHARACTERISTICS(1)

Symbol	Description	Test Conditions	Min.	Typ. <sup>(2)</sup>	Max.	Unit
t <sub>PLH</sub> (2)	LOW to HIGH Level Propagation Delay Time	AVDD = GND, OE = H, OS = L,		TBD		ns
		CLK to any output				
t <sub>PHL</sub> (2)	HIGH to LOW Level Propagation Delay Time	AVDD = GND, OE = H, OS = L,		TBD		ns
		CLK to any output				
tJIT(CC+)	Jitter (cycle-to-cycle)	166/200/266MHz	0		40	ps
t/IT(CC-)	1		0		-40	
tjit(per) <sup>(3)</sup>	Jitter (period)	166/200/266MHz	-40		40	ps
UIT(HPER) <sup>(3)</sup>	Half-Period Jitter	166/200/266MHz	-60		60	ps
tslr(0) <sup>(1,4)</sup>	Output Clock Slew Rate (single-ended)	166/200/266MHz (20% to 80%)	1.5	2.5	3	V/ns
tslr(1) <sup>(1,4)</sup>	Output Enable (OE)		0.5	_		V/ns
	Input Clock Slew Rate		1	2.5	4	
t(⊘) <sup>(5)</sup>	Static Phase Offset	166/200/266MHz	-50		50	ps
t(∅)DYN	Dynamic Phase Offset	166/200/266MHz	-50		50	ps
tsk(o)	Output Skew				40	ps
ten	Output Enable to any Y or $\overline{Y}$				8	ns
tois	Output Disable to any Y or $\overline{Y}$				8	ns
Vox <sup>(6)</sup>	AC Differential Output Crosspoint Voltage	Differential outputs terminated with $120\Omega$	(VDDQ/2)-0.1		(VDDQ/2)+0.1	V
VID(AC)	AC Differential Input Voltage		0.6		VDDQ+0.4	V
Vıx	AC Differential Input Crosspoint Voltage		(VDDQ/2)-0.15		(VDDQ/2)+0.15	V
The PLL on th	ne CSPU877D will meet all the above test parameters	while supporting SSC synthesizers with the fo	ollowing paramete	rs:	•	
SSC	Modulation Frequency		30		33	KHz
SSC	Clock Input Frequency Deviation		0	_	-0.5	%
f3dB	PLL Loop Bandwidth		2			MHz

### NOTES

- 1. There are two different terminations that are used with the above AC tests. The output load shown in figure 1 is used to measure the input and output differential pair cross-voltage only. The output load shown in figure 2 is used to measure all other tests, including input and output slew rates. For consistency, use 50Ω equal length cables with SMA connectors on the test board.
- 2. Refers to transition of non-inverting output.
- 3. Period jitter and half-period jitter specifications are seperate specifications that must be met independently of each other.
- 4. To eliminate the impact of input slew rates on static phase offset, the input slew rates of reference clock input (CLK, CLK) and feedback clock input (FBIN, FBIN) are recommended to be nearly equal. The 2.5V/ns slew rates are shown as a recommended target. Compliance with these nominal values is not mandatory if it can be adequately demonstrated that alternative characteristics meet the requirements of the registered DDR2 DIMM application.
- 5. Static phase offset does not include jitter.
- 6. Vox is specified at the DDR DRAM clock input or test load.

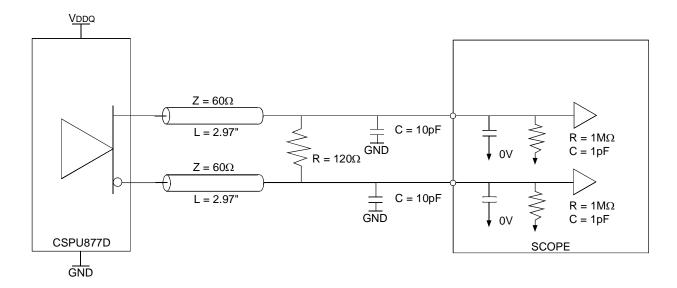


Figure 1: Output Load Test Circuit 1

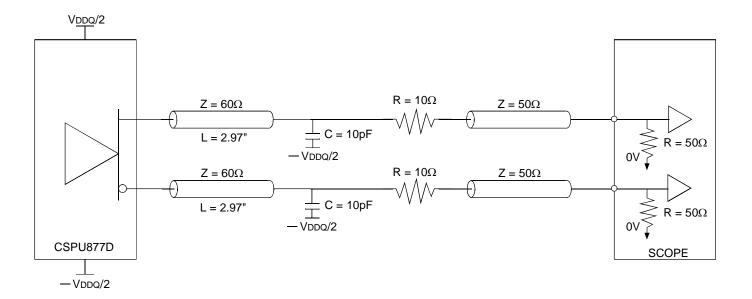
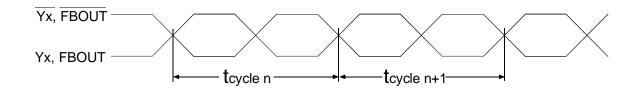
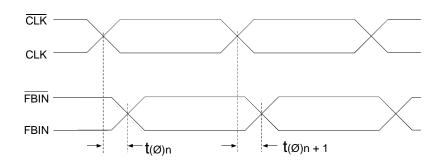


Figure 2: Output Load Test Circuit 2



$$t_{jit(cc)} = t_{cycle n} - t_{cycle n+1}$$

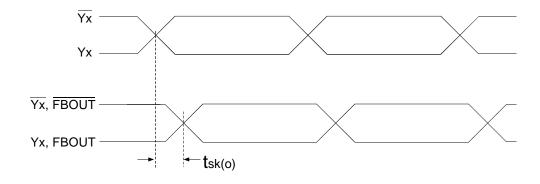
Cycle-to-Cycle jitter



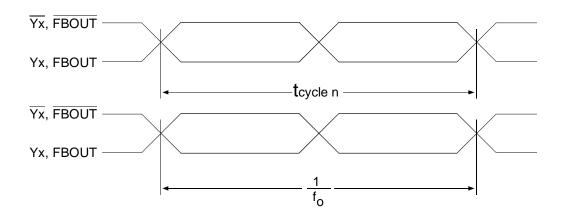
$$t(\emptyset) = \frac{\sum_{1}^{n=N} t(\emptyset)n}{N}$$

(N is a large number of samples)

**Static Phase Offset** 



**Output Skew** 

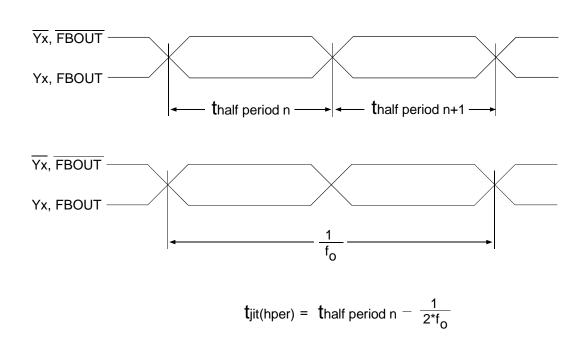


$$t_{jit(per)} = t_{cycle n} - \frac{1}{f_0}$$

### NOTE:

fo = Average input frequency measured at CLK / CLK

## Period jitter



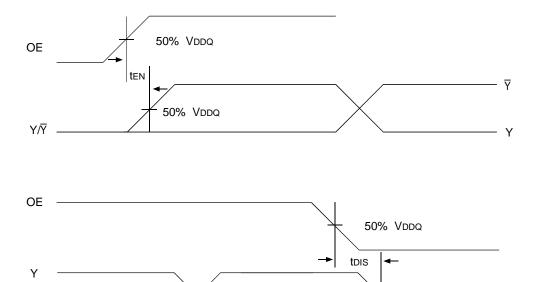
### NOTE:

fo = Average input frequency measured at CLK /  $\overline{\text{CLK}}$ 

Half-Period jitter

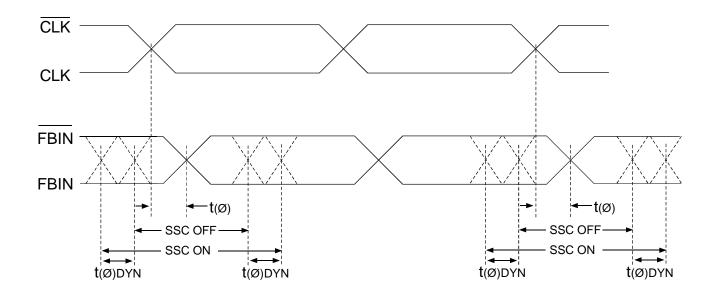
 $\overline{\mathsf{Y}}$ 

## TEST CIRCUIT AND SWITCHING WAVEFORMS

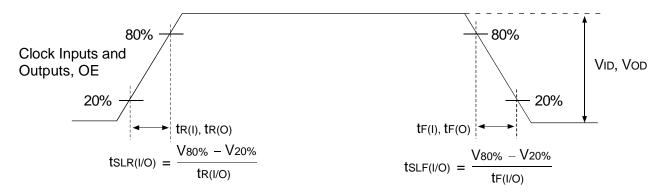


Time Delay Between Output Enable (OE) and Clock Output  $(Y, \overline{Y})$ 

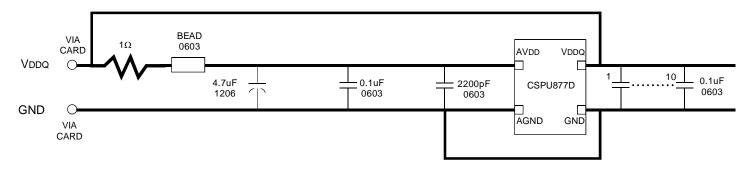
50% VDDQ



**Dynamic Phase Offset** 



Input and Output Slew Rates



### NOTES:

Place all decoupling capacitors as close to the CSPU877D pins as possible.

Use wide traces for AVDD and AGND.

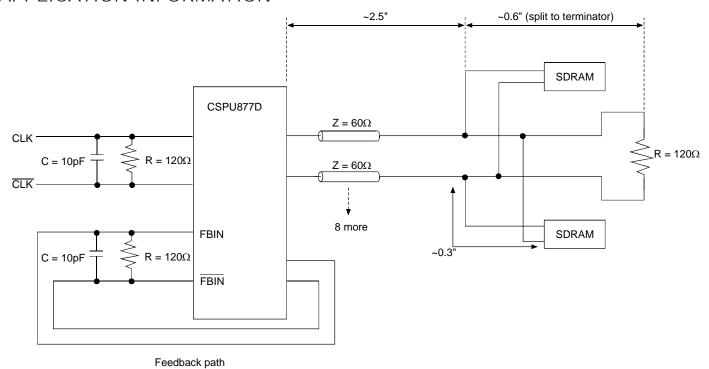
Recommended bead: Fair-rite P/N 2506036017Y0 or equivalent (0.8 $\Omega$  DC max., 600 $\Omega$  at 100MHz).

Recommended Filtering for the Analog and Digital Power Supplies (AVDD and VDDD)

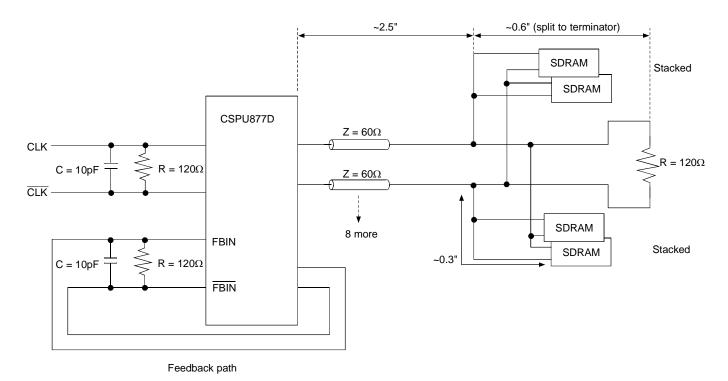
## APPLICATION INFORMATION

		Clock Loading on the PLL outputs (pF)		
Clock Structure	# of SDRAM Loads per Clock	Min.	Max.	
#1	2	3	5	
#2	4	6	10	

# APPLICATION INFORMATION

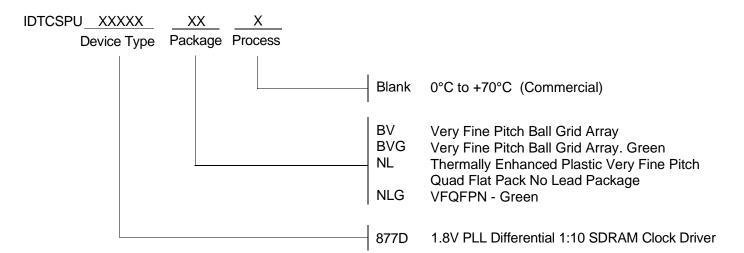


Clock Structure 1



**Clock Structure 2** 

## ORDERING INFORMATION





CORPORATE HEADQUARTERS

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800-345-7015 or 408-727-6116 fax: 408-492-8674 www.idt.com

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